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Specification for Approval

Customer:	_
Model Name:_	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

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Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2016-04-27	NEW ISSUE	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

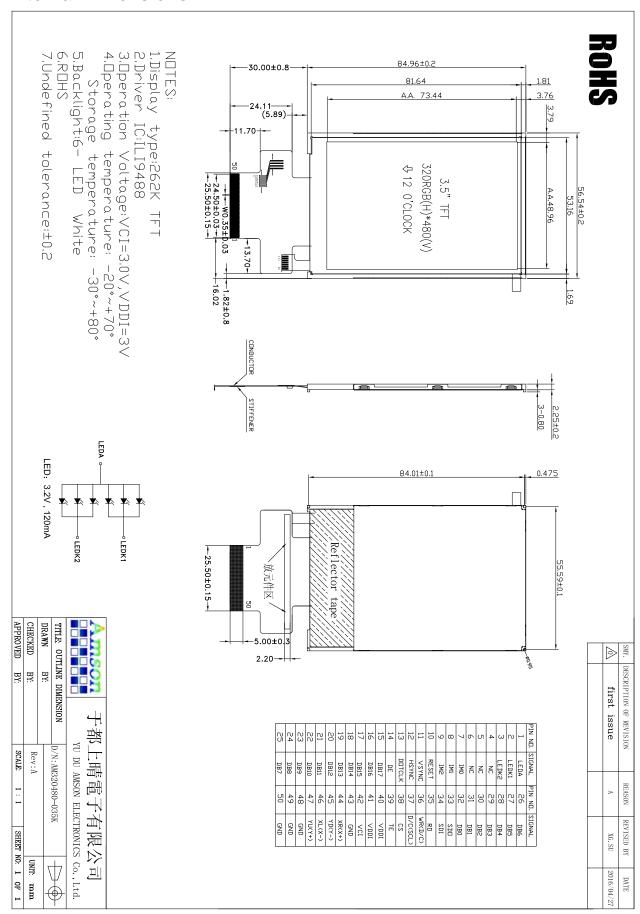
2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	3.5"TFT	
Dot arrangement	320(RGB)×480	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	-
Gray Scale Inversion Direction	12 O'clock	
Eyes Viewing Direction	6 O'clock	
Driver IC	ILI9488	
Module size	56.54(W)×84.96(H)×2.25 (T)	mm
Active area	48.96(W)×73.44(H)	mm
Dot pitch	0.153(W)×0.153(H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/ 9-/16-/18-bit 8080-series system interface 16-/18-bit RGB interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	6 White LEDS	
Weight	TBD	g

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3. External Dimensions





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4. Interface Description

4. Interi	ace Desc	ripuo	111				
PIN NO.	PIN NAME				DESCRIPTION		
1	LEDA	LED	backli	ght (A	node).		
2	LEDK1	LED	LED backlight (Cathode).				
3	LEDK2	LED	LED backlight (Cathode).				
4	NC	No co	onnec	ter			
5	NC	No co	onnec	ter			
6	NC	No co	No connecter				
_	13.40	Syste	m inte	rface	Mode		
7	IM0	IM2	IM2 IM1 IM0 Interface mode DB Pin				
		0	0	0	i80-system 18-bit interface	DB[17:0]	
8	IM1	0	0	1	i80-system 9-bit interface	DB[8:0]	
		0	1	0	i80-system 16-bit interface	DB[15:0]	
		0	1	1	i80-system 8-bit interface	DB[7:0]	
9	IM2	1	0	1	3-wires_9-bit SPI	/CS,SDI,SDO,SCL	
	IIVIZ	1	1	1	4-wires_8-bit SPI	/CS,RS,SDI,SDO,SCL	
10	/RESET	Rese	t inpu	t pin, <i>i</i>	Active "L".		
11	VSYNC	Vertic	al syn	c sign	al in RGB I/F.		
12	HSYNC		Horizontal sync signal in RGB I/F.				
13	DOTCLK		Pixel clock signal in RGB I/F.				
14	DE	Data 6	enable	e signa	al in RGB I/F mode		
15-32	DB17-DB0	8-bi 9-bi 16-b 24-b 18-bit 16-b 18-b	18-bit parallel bi-directional data bus for MPU system: 8-bit I/F: DB[7:0] is used. 9-bit I/F: DB[8:0] is used. 16-bit I/F: DB[15:0] is used. 24-bit I/F: DB[17:0] is used. 18-bit input data bus for RGB I/F. 16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0]; 18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0]; Connect unused pins to GND.				
33	SDO	Serial	outpu	ıt sign	al in SPI I/F.		
34	SDI	1	•		l in SPI I/F.		
35	/RD	Reads	strok	oe sigr	nal to write data when /RD is	"Low" in MPU interface.	
36	/WR_SCL		MCU: Serves as a write signal and writes data at the rising edge. SPI: SCL pin as Serial Clock when operates in the serial interface.				
37	DCX	Display data / command selection in 80-series MPU I/F. DCX = "0" : Command DCX = "1" : Display data.					
38	/CS	Chip s	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.				
39	TE	Tearin	g effe	ct out	put pin to synchronize MPU t	o frame writing.	
40	IOVCC	I/O po	wer s	upply.			
41	IOVCC	I/O pc	I/O power supply.				
42	VCI	Syste	System power supply.				
43	GND	Powe	r grou	nd			
44	XR	TP Ri	ght.				



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45	YD	TP Bottom.
46	XL	TP Left.
47	YU	TP Up.
48	GND	Power ground
49	GND	Power ground
50	GND	Power ground

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	3.3	V
Analog Supply Voltage	VCC	-0.3	3.3	٧
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

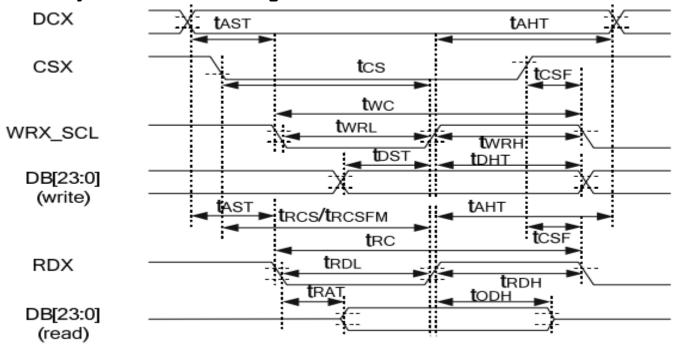
or bo orial actorication						
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	V	-
Analog Supply Voltage	VCC	2.5	2.8	3.3	V	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	V	-
Input Low Voltage	V _{IL}	GND	-	0.3IOVCC	V	-
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	V	-
Output Low Voltage	V _{OL}	GND	-	0.2IOVCC	V	-
I/O Leak Current	ILI	-1.0	-	1.0	uA	-

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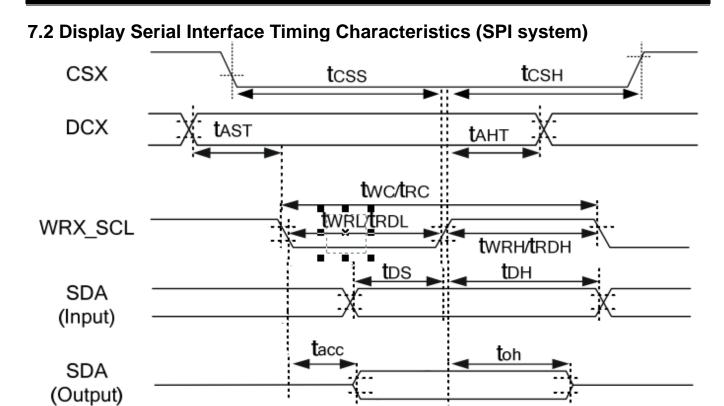
7. Timing Characteristics

7.1 i80-System Interface Timing Characteristics



Signal	Symbol	Parameter	Min.	Max.	Unit	Description
DCX	tast	Address setup time	0	-		
DCX	1	Address hold time (Write/Read)	10	-	ns	-
	tcs	Chip select setup time (Write)	10	-		
CSX	trcs	Chip select setup time (Read register)	45	-	ns	_
COA	trosem	Chip select setup time (GRAM)	355	-	115	_
	tcsf	Chip select wait time (Write/Read)	10	-		
	twc	Write cycle (write register)	50	-		
	twc	Write cycle (write GRAM@SLPOUT)	47	-		
_	twc	Write cycle (write GRAM@SLPIN)	100	-	ns	-
	twrn	Control pulse "H" duration	15	-		
twrl		Control pulse "L" duration	15	-		
	trc	Read cycle (read register)	160	-		
	trc	Read cycle (GRAM)	450	-		
RDX	tкон	Control pulse "H" duration	90	-	ns	-
	trol	Control pulse "L" duration(read register)	35	-		
	trol	Control pulse "L" duration(GRAM)	345	-		
	tost	Data setup time	10	-		
	toht	Data hold time	10	-		For maximum CL=30pF
DB[23:0]	t rat	Read access time(read register)	-	40	ns	For minimum CL=8pF
	trat	Read access time(GRAM)	-	340		l or minimum of-obi
	todh	Output disable time	20	80		

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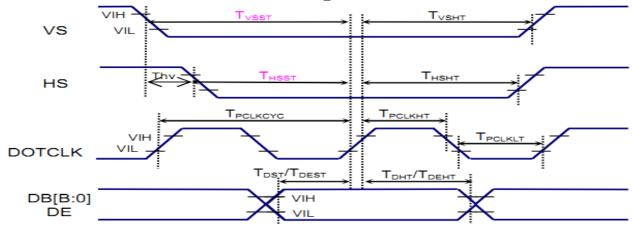


Signal	Symbol	Parameter	Min.	Max.	Unit	Description	
	tcss	Chip select setup time (Write)	15	-			
CSX	tcss	Chip select setup time (Read)	60	-	ne		
COA	tcsn	Chip select hold time (Write)	15	-	ns	_	
	tcsn	Chip select hold time (Read)	65	-			
DCX	tast	Address setup time	0	-			
DCX	I	Address hold time (Write/Read)	10	-	ns		
WRX SCL	twc	Write cycle	66	-			
_	twrn	Control pulse "H" duration	15	-	ns	-	
(Write) twee		Control pulse "L" duration	15	-			
WRX SCL	trc	Read cycle	150	-			
(Read)	tron	Control pulse "H" duration	60	-	ns	-	
(INeau)	trol	Control pulse "L" duration	60	-			
SDA	tos	Data setup time	10	-			
(Input)	tон	Data hold time	10	-	ns	For maximum CL=30pF	
SDA	tacc	Read access time	10	50	ne	For minimum C _L =8pF	
(Output)	tон	Output disable time	15	50	ns		

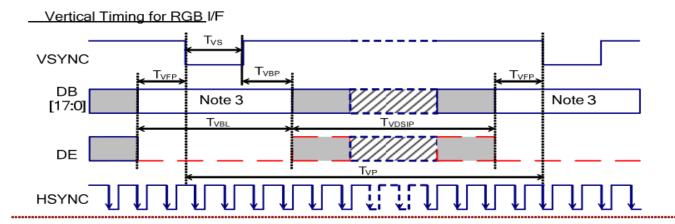
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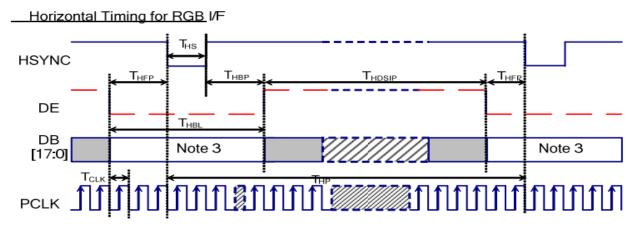
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7.3 Parallel 18-bit RGB Interface Timing Characteristics



Item	Symbol Condition			Unit		
item	Symbol	Condition	Min.	Тур.	Max.	Unit
Pixel low pulse width	T _{CLKLT}	-	15	-	-	ns
Pixel high pulse width	T _{CLKHT}	-	15	-	-	ns
Vertical Sync. Set-up time	T _{VSST}	-	15	-	-	ns
Vertical Sync. Hold time	T _{VSHT}	-	15	-	-	ns
Horizontal Sync. Set-up time	T _{HSST}	-	15	-	-	ns
Horizontal Sync. Hold time	T _{HSHT}	-	15	-	-	ns
Data Enable set-up time	T _{DEST}	-	15	-	-	ns
Data Enable hold time	T _{DEHT}	-	15	-	-	ns
Data set-up time	T _{DST}	-	15	-	-	ns
Data hold time	T _{DHT}	-	15	-	-	ns
Phase difference of sync signal falling edge	Thv	-	0	-	320	Dotclk





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ltem	Complete	Condition		Specificatio	n	Unit
item	Symbol	Condition	Min.		Max.	Unit
Vertical Timing						
	VP	_	486	-	-	HS
Vertical low pulse width	T _{VS}					
Vertical front porch	T _{VFP}	-	2	-	-	HS
Vertical back porch	T _{VBP}	-	2	-	-	HS
Vertical blanking period	T _{VBL}	T _{VS} + T _{VBP} + T _{VFP}	6	-	-	HS
			-		-	HS
Vertical active area	T _{VDISP}	-	-	480	-	HS
			-		•	HS
Vertical refresh rate	T _{VRR}	Frame rate	50	60	70	Hz
Horizontal Timing						
Horizontal cycle period	T _{HP}	-	335	-	-	DOTCLK
Horizontal low pulse width	T _{HS}	-	5	-	•	DOTCLK
Horizontal front porch	T _{HFP}	-	5	-	•	DOTCLK
Horizontal back porch	T _{HBP}	-	5	-	-	DOTCLK
Horizontal blanking period	T _{HBL}	T _{HS} +T _{HBP} + T _{HFP}	15	-	-	DOTCLK
Horizontal active area	THDISP	-	-	320	-	DOTCLK
Pixel clock cycle TVRR=60Hz	f _{CLKCYC}	-	9	-	-	MHz

Note: (1) IOVCC=1.65 to 3.3V, VCI=2.3 to 3.3V, VSSA=VSSD=0V, Ta=-30 to 70°C (to +85°C no damage)

- (2) Data lines can be set to "High" or "Low" during blanking time Don't care.
- (3) HP is multiples of PCLK.

7.4 Reset Timing Characteristics

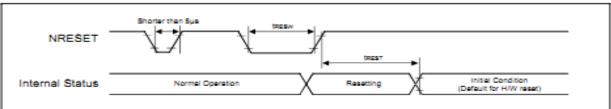


Figure 8.4: Reset input timing

Symbol	Parameter	Related	Spec.			Note	Unit
dymbol	r ai ailletei	Pins	Min.	Typ.	Max.	Note	Omit
tRESW	Reset low pulse width ⁽¹⁾	NRESET	10	-	-	-	βЩ
tREST	Reset complete time ⁽²⁾	•	5	1	-	When reset applied during SLPIN mode	ms
TREST		1	120	1	1	When reset applied during SLPOUT mode	ms

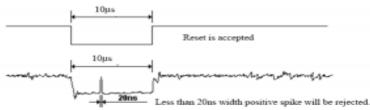
Table 8.7: Reset input timing

Note: (1) Spike due to an electrostatic discharge on NRESET line does not cause irregular system reset according to the following table.

NRESET Pulse	Action		
Shorter than 5 µs	Reset Rejected		
Longer than 10 µs	Reset		
Between 5 µs and 10 µs	Reset Start		

- (2) During the resetting period, the display will be blanked (The display is entering blanking sequence, which Maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then return to Default condition for H/W reset.
- In -mode) and then return to Default condition for H/W reset.

 (3) During Reset Complete Time, ID and VCOM value in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (tREST) within 5ms after a rising edge of NRESET.
- (4) Spike Rejection also applies during a valid reset pulse as shown as below:

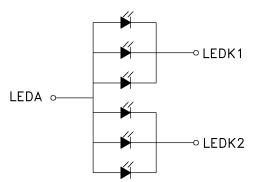


 It is necessary to wait 5msec after releasing NRESET before sending commands. Also Sleep Out command cannot be sent for 120msec.

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Backlight Characteristics



LED: 3.2V, 120mA

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.8	3.2	3.4	V	lf=120mA
Supply Current	If	-	120	-	mA	-
Luminous Intensity for LCM	-	300	400	-	cd/m ²	If=120mA
Uniformity for LCM	-	80	-	-	%	lf=120mA
Life Time	-	20000	-	-	Hr	If=120mA
Backlight Color	White					



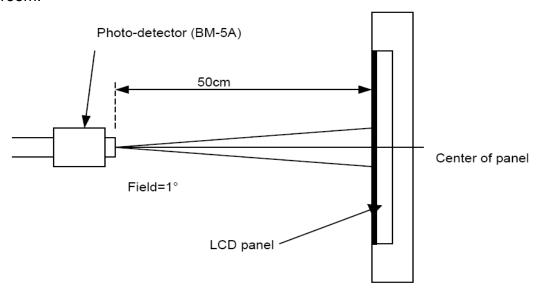
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9. Optical Characteristics

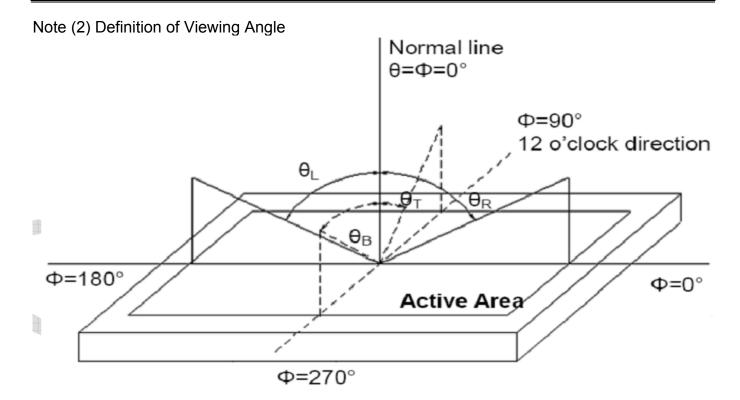
Item	Conditions		Min.	Тур.	Max.	Unit	Note	
	Horizontal	θL	60	70	-			
Viewing Angle	HOHZOHIAI	θR	60	70	-	dograa	(1) (2) (6)	
(CR>10)	Vertical	θт	60	70	-	degree	(1),(2),(6)	
	vertical	θв	40	60	-			
Contrast Ratio	Center		400	500	-	-	(1),(3),(6)	
Doonongo Timo	Rising		-	(4)	(8)	ms	(1) (4) (6)	
Response Time	Falling			(12)	(24)		(1),(4),(6)	
	Red x			0.626		1		
	Red y			0.334		-		
	Green x			0.277		-		
CF Color	Green y		Тур.	0.549	Тур.	-	(1) (6)	
Chromaticity (CIE1931)	Blue x		-0.05	0.142	+0.05	-	(1), (6)	
,	Blue y			0.122		-		
	White x			0.303		-		
	White y			0.325		-		

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



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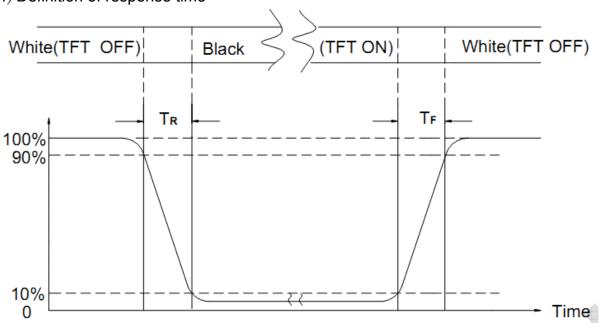


Note (3) Definition of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD



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10. Reliability Test Conditions and Methods

No change on display and in operation under the following test condition.

Condition: Unless otherwise specified, tests will be conducted under the following condition.

Temperature: 20±5°C Humidity: 65±5%RH Tests will be not conducted under functioning state.

No.	Parameter	Condition	Notes
1	High Temperature Operating	70°C±2°C, 240hrs (Operation state)	
2	Low Temperature Operating	-20°C±2°C, 240hrs (Operation state)	
3	High Temperature Storage	80°C±2°C, 240hrs	
4	Low Temperature Storage	-30°C±2°C, 240hrs	
5	High Temperature and High Humidity Operation Tes t	60°C±2°C, 90%, 240hrs	
6	Vibration Test	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 direction of X, Y, Z each 15 minutes.	
7.	Drop Test	To be measured after dropping from 60cm high on the concrete surface in packing state. F Dropping method corner dropping A corner: once Edge dropping B, C, D edge: once Face dropping E, F, G face: once Concrete Surface	

Notes:

- 1. No dew condensation to be observed.
- 2. The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.
- 3. Vibration test will be conducted to the product itself without putting I in a container.



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11. Inspection Standard

11.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

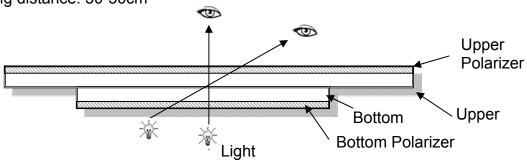
Temperature: 25±5°C

Humidity: 65%±10%RH

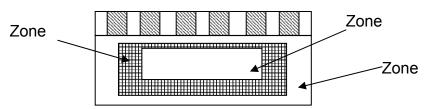
Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance: 30-50cm



11.1.2 Definition



Zone A: Effective Viewing Area (Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A + Zone B) which cannot be seen after assembly by customer.)

Note:

As a general rule, visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

11.1.3 Sampling Plan

According to GB/T 2828-2003; normal inspection, Class $\, \mathrm{II} \,$ AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display, TP: Touch Panel, LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. TP no function 	Major
2	Missing	Missing component	Wajoi
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	



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4	Color tone	Color unevenness, refer to limited sample	
5	Soldering appearance	Good soldering, Peeling off is not allowed.	Minor
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

11.1.4 Crite	11.1.4 Criteria (Visual)								
Number	Items	Criteria(mm)							
	(1) The edge of LCD broken	X Y Z							
		≤3.0mm							
1.0 LCD Crack / Broken NOTE: X: Length Y: Width Z: Height L: Length of ITO, T: Height of LCD	(2)LCD corner broken	X Y Z ≤3.0mm ≤L ≤T							
	(3) LCD crack	Crack Not allowed							



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Number	Items	Criteria (mm)						
		① light dot (LCD	/TP/Polarizer	black/white	spot , light d	ot, pinhole,		
		dent, stain)						
		Zone	Ac	ceptable Q	ty			
		Size (mm)	Α	В	С			
		Ф≤0.10	Igno	re				
		0.10<Φ≤0.15	3(distance	≥10mm)	gnore			
		0.15<Φ≤0.2	1		gnore			
		0.2<Ф	0					
	Spot defect	②Dim spot(LCI				dark spot)		
	Y ↑	Zone	Ac	ceptable Q	ty 			
		Size (mm)	Α	В	С			
		Ф≤0.1	Igno	re				
	 ≺ → X	0.1<Φ≤0.2	2(distance≥10mm)		gnore			
	Ф=(X+Y)/2	0.2<Φ≤0.3	0.2<Φ≤0.3 1		gnore			
2.0		Ф>0.3	0					
		③ Polarizer accidented spot						
		Zone	A	cceptable C	ety			
		Size (mm)	А	В	С			
		Ф≤0.2	Ignore					
		0.2<Φ≤0.5	2(distance ≥ 10mm)		Ignore			
		Ф>0.5	0)				
						_		
		\\/idth/mm\	Length(m	Accep	table Qty			
	Line defect	Width(mm)	m)	А	ВС			
	(LCD/TP /Polarizer	Ф≤0.03	Ignore	Ignore				
	black/white line, scratch, stain)	0.03 <w≤0.05< td=""><td>L≤3.0</td><td>N≤2</td><td>Ignore</td><td></td></w≤0.05<>	L≤3.0	N≤2	Ignore			
		0.05 <w≤0.08< td=""><td>L≤2.0</td><td>N≤2</td><td></td><td></td></w≤0.08<>	L≤2.0	N≤2				
		0.08 <w< td=""><td>Defi</td><td>ne as spot</td><td>defect</td><td></td></w<>	Defi	ne as spot	defect			
				_	_	_		



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					1		
		Zone	,	Qty			
		Size (mm)	Α	В	С		
3.0	Polarizer	Ф≤0.2	lgr	nore			
3.0	Bubble	0.2<Φ≤0.4	2(distance≧10mm)		Ignore		
		0.4<Φ≤0.6	1				
		0.6<Ф	0				
4.0	SMT	According to IPC-A-610C class ${\rm II}$ standard. Function defect and missing part are major defect, the others are minor defect.					



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to power or ground, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



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12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method